

# WEIDACHENG INDUSYRY CO.,LTD

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## SOLDERING PLACEMENT' SYSTEM BU-510

Ball placement capability:  $\Phi 0.4 \sim \Phi 0.76$  Ball placement range:L-60mm.W-80mm



All kinds of solder ball placement tooling for BGA IC.

Solder ball collecting bottle base. (Ball cleaning device)

